

L Number	Hits	Search Text	DB	Time stamp
1	61	plug\$4 with (hole via spac\$3 open\$4) and ((circuit adj pattern) trace) and ((doctor with blad\$3) squeegee) and (resist dielectric insulat\$3)	USPAT; EPO; JPO	2004/02/20 10:07
2	6	plug\$4 with (hole via spac\$3 open\$4) same ((circuit adj pattern) (conductive adj trace)) same (resist dielectric insulat\$3) and ((doctor with blad\$3) squeegee)	USPAT; EPO; JPO	2004/02/20 10:10
3	65	plug\$4 with (hole via spac\$3 open\$4) same (resist dielectric insulat\$3) and ((doctor with blad\$3) squeegee)	USPAT; EPO; JPO	2004/02/20 10:21
4	789	(fill\$3 plug\$4) with (hole via spac\$3 open\$4) same (solder adj resist insulating adj resin)	USPAT; EPO; JPO	2004/02/20 10:22
5	29	((fill\$3 plug\$4) with (hole via spac\$3 open\$4) same (solder adj resist insulating adj resin)) and ((doctor with blad\$3) squeegee)	USPAT; EPO; JPO	2004/02/20 10:38
7	997	29/\$.ccls. and ((doctor with blad\$3) squeegee)	USPAT; EPO; JPO	2004/02/20 10:38
8	48	29/\$.ccls. and ((doctor with blad\$3) squeegee) and (solder adj resist insulating adj resin)	USPAT; EPO; JPO	2004/02/20 12:03
9	44	427/\$.ccls. and ((doctor with blad\$3) squeegee) and (solder adj resist insulating adj resin)	USPAT; EPO; JPO	2004/02/20 12:21
10	0	63318798.URPN.	USPAT	2004/02/20 12:21
11	8	427/\$.ccls. and ((doctor with blad\$3) squeegee) and (hole spac\$3 via open\$4) with solder adj resist	USPAT; EPO; JPO	2004/02/20 12:22
12	8	((doctor with blad\$3) squeegee) and (plug\$4 fill\$3) with (hole spac\$3 via open\$4) with solder adj resist	USPAT; EPO; JPO	2004/02/20 12:24
13	24	((doctor with blad\$3) squeegee) same (hole spac\$3 via open\$4) with solder adj resist	USPAT; EPO; JPO	2004/02/20 12:27
14	618	((doctor with blad\$3) squeegee) same (hole via) with (plug\$4 fill\$3)	USPAT; EPO; JPO	2004/02/20 12:28
15	4	((doctor with blad\$3) squeegee) same (hole via) with (plug\$4 fill\$3) with solder adj resist	USPAT; EPO; JPO	2004/02/20 12:29
16	0	((doctor with blad\$3) squeegee) same (hole via) with (plug\$4 fill\$3) with insulating adj resin	USPAT; EPO; JPO	2004/02/20 12:30
17	23	((doctor with blad\$3) squeegee) same (hole via) with (plug\$4 fill\$3) with insulating	USPAT; EPO; JPO	2004/02/20 15:19
18	18	4715117.URPN.	USPAT	2004/02/20 12:32
19	27	4792646.URPN.	USPAT	2004/02/20 12:34
20	37	("3613230"   "4017968"   "4319708"   "4681649"   "4704791"   "4791248"   "4792646"   "4967314"   "4983252"   "5006182"   "5028743"   "5117069"   "5118458"   "5146674"   "5153986"   "5224265"   "5243142"   "5271150"   "5288665"   "5346750"   "5421083"   "5443672"   "5450290"   "5451722"   "5487218"   "5557844"   "5568682"   "5571593"   "5662987"   "5665650"   "5666722"   "5685070"   "5689091"   "5740606"   "5745984"   "5779836"   "5822856").PN.	USPAT	2004/02/20 12:39
34	158	((doctor with blad\$3) squeegee) same (hole via) and (no without) with (mask tencil)	USPAT; EPO; JPO	2004/02/20 15:21

35	10	((doctor with blad\$3) squeegee) same (hole via) and (no without) with (mask tencil)) and (fill\$3 plug\$4) with insulating	USPAT; EPO; JPO	2004/02/20 15:26
36	5	((doctor with blad\$3) squeegee) same (hole via) and (no without) with (mask tencil)) and (fill\$3 plug\$4) with resist	USPAT; EPO; JPO	2004/02/20 15:28
37	24	((doctor with blad\$3) squeegee) same (hole via) and (no without) with (mask tencil)) and (fill\$3 plug\$4) with resin	USPAT; EPO; JPO	2004/02/20 15:35
38	112	((doctor with blad\$3) squeegee) same (hole via) and (no without) with (mask tencil)) and (fill\$3 plug\$4)	USPAT; EPO; JPO	2004/02/20 16:18
39	1	4728568.pn.	USPAT; EPO; JPO	2004/02/20 16:18
40	12	4728568.URPN.	USPAT	2004/02/20 16:19
41	6	("3758433"   "3948701"   "4166150"   "4255208"   "4448622"   "4503098").PN.	USPAT	2004/02/20 16:20
-	4	hole with plug\$4.ti. and Lee.in.	USPAT; EPO; JPO	2003/11/17 12:11
-	5	hole with plug\$4.ti. and Lee.in.	USPAT; US-PGPUB; EPO; JPO	2003/11/17 12:12
-	1	circuit adj board.ti. and air adj space and void adj formed	USPAT; EPO; JPO	2003/11/17 12:13
-	14	("4293377"   "4360570"   "5252195"   "5284548"   "5308929"   "5309632"   "5690837"   "5863447"   "6097089"   "6228511"   "6242078"   "6282782"   "6323436"   "6376158").PN.	USPAT	2003/12/03 17:37
-	7	(hole via) with plug\$4 and ((solder adj resist) (insulating adj resin)) and squeegee	USPAT; EPO; JPO	2003/12/03 17:47
-	1	RE32430.URPN.	USPAT	2003/12/03 17:50
-	9	("3629036"   "3824104"   "3904492"   "3984244"   "4127436"   "4230793"   "4234626"   "4260675"   "4344998").PN.	USPAT	2003/12/03 17:50
-	21	4506004.URPN.	USPAT	2003/12/03 17:51
-	8	("3629036"   "3824104"   "3984244"   "4127436"   "4230793"   "4234626"   "4260675"   "4344998").PN.	USPAT	2003/12/03 17:53
-	19	4804615.URPN.	USPAT	2003/12/03 17:53
-	22	5729437.URPN.	USPAT	2003/12/03 17:55
-	14	("4942364"   "5446309"   "5539241"   "5742091"   "5844299"   "5877533"   "5883335"   "5898223"   "5977845"   "6002161"   "6108212"   "6180995"   "6258688"   "6287931").PN.	USPAT	2003/12/03 17:57
-	1	6631838.pn.	USPAT; EPO; JPO	2003/12/04 17:25
-	49	plug\$4 with hole and squeegee and mask\$3	USPAT; EPO; JPO	2003/12/04 17:27
-	49	4964948.URPN.	USPAT	2003/12/04 17:39
-	8	("3370351"   "4521449"   "4715117"   "4817276"   "4925723"   "4964947"   "4964948"   "5120384").PN.	USPAT	2003/12/04 17:45
-	11	5274916.URPN.	USPAT	2003/12/04 17:46
-	43	(solder adj resist insulating adj resin) and (squeegee doctor adj blade) and circuit adj pattern and (hole via)	USPAT; EPO; JPO	2004/02/19 17:23
-	11	("4668532"   "4786528"   "5382333"   "5439986"   "5652042"   "5670250"   "5888627"   "6060150"   "6214455"   "6355131"   "6524717").PN.	USPAT	2004/02/19 12:29

-	2	("3948706"   "4024629").PN.	USPAT	2004/02/19 14:16
-	50	4024629.URPN.	USPAT	2004/02/19 14:16
-	1	RE32430.URPN.	USPAT	2004/02/19 16:50
-	9	("3629036"   "3824104"   "3904492"   "3984244"   "4127436"   "4230793"   "4234626"   "4260675"   "4344998").PN.	USPAT	2004/02/19 16:50
-	1	6139904.pn.	USPAT; EPO; JPO	2004/02/19 16:53
-	5	("3158503"   "4323593"   "4401686"   "4529477"   "4763403").PN.	USPAT	2004/02/19 17:09
-	18	4529477.URPN.	USPAT	2004/02/19 17:10
-	18	4529477.URPN.	USPAT	2004/02/19 17:11
-	2	("4323593"   "4324815").PN.	USPAT	2004/02/19 17:11
-	32	4323593.URPN.	USPAT	2004/02/19 17:11
-	5	("4323593"   "4964948"   "5191709"   "5268194"   "5822856").PN.	USPAT	2004/02/19 17:12
-	50	4964948.URPN.	USPAT	2004/02/19 17:14
-	11	((solder adj resist) (insulating adj resin)) same fill\$3 same (hole via) and (squeegee (doctor adj blad\$3)) and circuit adj pattern	USPAT; EPO; JPO	2004/02/19 17:28
-	29	((solder with resist) (insulating with resin)) same fill\$3 same (hole via open\$3 spac\$3) and (squeegee (doctor adj blad\$3)) and circuit adj pattern	USPAT; EPO; JPO	2004/02/19 17:32
-	583	29/846,852.ccls. and fill\$3 with (via hole open\$3 spac\$3)	USPAT; EPO; JPO	2004/02/19 17:36
-	60	(29/846,852.ccls. and fill\$3 with (via hole open\$3 spac\$3)) and solder with resist	USPAT; EPO; JPO	2004/02/19 17:34
-	88	29/846,852.ccls. and fill\$3 and (squeegee (doctor adj blad\$3))	USPAT; EPO; JPO	2004/02/19 17:37
-	4	("4323593"   "5277761"   "5323701"   "5821179").PN.	USPAT	2004/02/19 17:38
-	4	("5659951"   "5876842"   "6175087"   "6300575").PN.	USPAT	2004/02/19 17:40
-	7	("5014111"   "5274916"   "5384952"   "5407864"   "5615477"   "5843251"   "5848466").PN.	USPAT	2004/02/19 17:44
-	32	4323593.URPN.	USPAT	2004/02/19 18:01
-	9	5120384.URPN.	USPAT	2004/02/19 18:03
-	4	("3354542"   "4336100"   "4732636"   "4902551").PN.	USPAT	2004/02/19 18:04
-	13	("4090231"   "4109377"   "4396936"   "4919970"   "5189261"   "5427865"   "5463191"   "5492266"   "5561322"   "5593080"   "5620129"   "5759269"   "5803340").PN.	USPAT	2004/02/19 18:05
-	15	("5041183"   "5260170"   "5286926"   "5375042"   "5378869"   "5389742"   "5466892"   "5473120"   "5495665"   "5510216"   "5576519"   "5600103"   "5744758"   "5876842"   "6010769").PN.	USPAT	2004/02/19 18:09
-	7	5268194.URPN.	USPAT	2004/02/19 18:12
-	6	("4145691"   "4323593"   "4324815"   "4664945"   "4938994"   "5133120").PN.	USPAT	2004/02/19 18:12
-	50	4024629.URPN.	USPAT	2004/02/19 18:16
-	2	5087413.URPN.	USPAT	2004/02/19 18:23

-	8	("3852877"   "4024629"   "4434134"   "4599277"   "4671928"   "4868034"   "4954313"   "4961879").PN.	USPAT	2004/02/19 18:23
-	16	4919970.URPN.	USPAT	2004/02/19 18:24
-	12	("3226255"   "3735730"   "4020206"   "4023487"   "4024629"   "4127337"   "4323593"   "4459320"   "4515304"   "4529477"   "4604966"   "4761881").PN.	USPAT	2004/02/19 18:26
-	6	("3077511"   "4024629"   "4249302"   "4604160"   "4663497"   "4792646").PN.	USPAT	2004/02/19 18:27
-	11	("2964007"   "3516155"   "4311267"   "4323593"   "4626309"   "4694138"   "4739919"   "4774760"   "4872261"   "4953460"   "5129573").PN.	USPAT	2004/02/19 18:37
-	25	5593080.URPN.	USPAT	2004/02/19 18:37

 Details
  Text
  Image
  HTML

US 5385868 A	19950131	Upward plug process for metal via holes	438/637	
US 4961390 A	19901009	Perforated plugs for air holes in a rotary combustor	110/246	
US 6372616 B1	20020416	Method of manufacturing an electrical interconnection of a semiconductor device using an erosion protection	438/592	Chao, Ying-Chen et al.
US 20020184757 A	20021212	Hole plugging method for printed circuit boards, and hole plugging device	29/852	Whitlow, Graham A. et al.
US 6631838 B2	20031014	Method for fabricating printed circuit board	228/225	Yoo, Bong-young et al.
US 6282782 B1	20010904	Forming plugs in vias of circuit board layers and subassemblies	29/852	Lee, Sung Gue et al.
US 6376158 B1	20020423	Methods for selectively filling apertures	430/315	Kim, Nam-Jin et al.
US RE32430 E	19870602	Printed wiring board	430/312	Biunno, Nicholas et al.
US 6504227 B1	20030107	Passive semiconductor device mounted as daughter chip on active semiconductor device	257/531	Jones, Gerald Walter et al.
US 4804615 A	19890214	Method for manufacture of printed circuit boards	430/314	Sullivan, Donald F.
US 5729437 A	19980317	Electronic part including a thin body of molding resin	361/760	Matsuo, Mie et al.
US 5665525 A	19970909	Method for producing printed circuit boards	430/315	Larson, Gary B. et al.
US 5324535 A	19940628	Process of coating printed wiring board with solid solder resist pattern formed from liquid and dry solder	427/76	Hashimoto, Nobuaki
US 6276055 B1	20010821	Method and apparatus for forming plugs in vias of a circuit board layer	29/852	Pienimaa, Seppo
US 6264862 B1	20010724	Method for manufacturing a plug	264/102	Ishido, Kiminori
US 4964948 A	19901023	Printed circuit board through hole technique	216/18	Bryan, Scott K. et al.
US 5229549 A	19930720	Ceramic circuit board and a method of manufacturing the ceramic circuit board	174/262	Liaw, Been-Yu
US 6139904 A	20001031	Method of making a printed board	427/97	Reed, Ronald G.
US 5274916 A	19940104	Method of manufacturing ceramic multilayer electronic component	29/848	Yamakawa, Akira et al.
US 4715117 A	19871229	Ceramic wiring board and its production	29/851	Yamasaki, Kozo et al.
US 6051093 A	20000418	Mounting method of semiconductor element	156/251	Kawabata, Shoichi et al.
US 6381838 B1	20020507	BGA package and method of manufacturing the same	29/848	Enomoto, Eyo
US 6329610 B1	20011211	Hybrid wiring board, semiconductor apparatus, flexible substrate, and fabrication method of hybrid wiring	174/264	Tsukahara, Norihito
US 5832600 A	19981110	Method of mounting electronic parts	29/841	Ahn, Eun Chul et al.
US 5662987 A	19970902	Multilayer printed wiring board and method of making same	428/209	Takubo, Chiaki et al.
US 5304392 A	19940419	Method of manufacturing printed wiring board	427/96	Hashimoto, Nobuaki
US 5268194 A	19931207	Method of packing filler into through-holes in a printed circuit board	427/97	Mizumoto, Shogo et al.
US 5145691 A	19920908	Apparatus for packing filler into through-holes or the like in a printed circuit board	425/110	Matsumoto, Masuo
US 5090120 A	19920225	Process for forming solder lands in a printed wiring board manufacturing method	29/846	Kawakami, Shin et al.
US 4323593 A	19820406	Method of printing a spot pattern in a printed circuit board	427/97	Kawakami, Shin et al.
US 4024629 A	19770524	Fabrication techniques for multilayer ceramic modules	29/852	Matsumoto, Masuo
US 5087413 A	19920211	Conducting material and a method of fabricating thereof	419/9	Tsunashima, Eiichi
US 4919970 A	19900424	Solder deposition control	427/96	Lemonie, Jean Marie et al.
US 4908940 A	19900320	Method of manufacturing two-layer printed circuit sheet	29/852	Abe, Kenichiro
US 4383495 A	19830517	Apparatus for coating surfaces of a substrate	118/406	Hoebener, Karl G. et al.
US 6060150 A	20000509	Sheet for a thermal conductive substrate, a method for manufacturing the same, a thermal conductive substrate	428/209	Amano, Toshiaki et al.
US 5120384 A	19920609	Method of manufacturing multilayer laminate	156/242	Plichta, George J. et al.